

Docket No.: 300.1152

Serial No. 10/821,915

IN THE TITLE:

The TITLE as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~strikethrough~~.

SEMICONDUCTOR PACKAGE AND PRODUCTION METHOD

Docket No.: 300.1152

Serial No. 10/821,915

IN THE SPECIFICATION:

The specification as amended below with replacement paragraphs shows added text with underlining and deleted text with ~~strikethrough~~.

Please REPLACE the paragraph beginning at page 19, line 15, with the following paragraph:

After resin sealing is complete, the heat radiation layer 31-32 is further formed on the back protective film 31 formed in the preceding step as shown in Fig. 6L. This step can be advantageously carried out by sputtering aluminum (Al) as a material having a high heat transfer rate, for example.